## FLIP CHIP MODULES TEST SPECS

TYPE: WO51

RELAY DRIVER

TEST	CONDITIONS	MAXIMUM	MINIMUM
V <sub>CE</sub> (SAT.)	2.0V IN	400 MV	
LOWER LEVEL	0.5V IN 150Ω TO -15 LOAD	-15.1 V	-14.9 V
INPUT CURRENT FROM GROUND	PIN V ONLY	2.7 - 3.3 MA	
RISE TTT	150Ω TO -15V LOAD 100 CPS, FF INPUT	1.0	
FALL TTT	50Ω TO -15V LOAD 100 CPS, F INPUT	1.0 µs	
CLAMP DIODE FWD DROP	FWD CURRENT OF 100 MA.	1.0	0.5 V

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION 3/4/66 R.)

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep he copper from lifting.

Decilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.